

INTERNATIONAL STANDARD



**Test methods for electrical materials, printed board and other interconnection structures and assemblies –
Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards**

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CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Normative references	6
3 Terms and definitions	6
4 Testing condition	7
4.1 Standard condition	7
4.2 Judgment state	8
5 Specimen	8
5.1 Outline of CAF test vehicle design	8
5.1.1 Evaluation design for the glass cloth direction	8
5.1.2 Design between plated through hole (PTH).....	9
5.2 CAF test board.....	10
5.2.1 Example A.....	10
5.2.2 Example B.....	11
5.3 Number of specimens	13
6 Equipment/Apparatus or material.....	13
6.1 Environmental test chamber.....	13
6.2 Measuring equipment.....	13
6.3 Power supply	13
6.4 Current limiting resistors	14
6.5 Connecting wire	14
6.6 Other dedicated fixtures	14
7 Resistance measurement method	14
7.1 Manual insulation resistance measurement method	14
7.2 Automatic insulation resistance measurement method	15
8 Test method	16
8.1 Test method selection	16
8.2 Steady-state temperature and humidity test	16
8.2.1 Object.....	16
8.2.2 Test condition	16
8.3 Temperature and humidity (12 h + 12 h) cycle test.....	16
8.3.1 Object.....	16
8.3.2 Test condition	17
8.3.3 Number of cycles of the test	17
8.4 Temperature and humidity cyclic test with and without low temperature exposure.....	17
8.4.1 Object.....	17
8.4.2 Test condition	17
8.5 Steady-state high temperature and high humidity (unsaturated pressurized vapour) test	17
8.5.1 Object.....	17
8.5.2 Test condition	18
9 Procedure.....	18
9.1 Test specimen preparation.....	18
9.1.1 General	18
9.1.2 Sample identification	18

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 IEC 61189-5-503:2017
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9.1.3	Prescreen for opens and shorts	18
9.1.4	Cleaning	19
9.1.5	Connecting wire	19
9.1.6	Cleaning after attachment	19
9.1.7	Dry	19
9.2	Precondition	19
9.3	Test procedure	19
9.3.1	Setting of the specimen	19
9.3.2	Test voltage and measuring voltage	19
9.3.3	Temperature and humidity condition at the start time of the test	20
9.3.4	Measurement	20
9.3.5	Procedure in test interruption	21
9.3.6	End of test	21
9.4	Visual inspection	21
9.4.1	General	21
9.4.2	Shape of electrochemical migration	21
Annex A (informative)	Forms of electrochemical migration	22
A.1	Example of dendrite-shaped migration	22
A.2	CAF (Example of migration along the glass fibre)	22
Bibliography	23
Figure 1	– Schematic of in-line test comb, with possible failure site	8
Figure 2	– Schematic of staggered test comb, with possible failure site	9
Figure 3	– Manhattan distance	9
Figure 4	– Schematic section of via pair with bias	10
Figure 5	– Example of inner layer via pads and layer patterns	10
Figure 6	– Example of no inner layer via pads and layer patterns	10
Figure 7	– Insulation evaluation pattern for through-holes and via holes	11
Figure 8	– Layouts of the two versions of the CAF test boards	12
Figure 9	– Measurement with insulation resistance meter	15
Figure 10	– Temperature and humidity in a test	20
Figure A.1	– Example which is generated on the board surface	22
Figure A.2	– Example of CAF	22
Table 1	– Dimension of insulation evaluation pattern for through-holes	11
Table 2	– Test structures A1 through A4 design rules	12
Table 3	– Test structures B1 through B4 design rules	13
Table 4	– Test condition	16
Table 5	– Number of cycles of the test	17
Table 6	– Test condition	17
Table 7	– Test condition (IEC 60068-2-66)	18

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**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD
AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 5-503: General test method for materials and assemblies –
Conductive anodic filaments (CAF) testing of circuit boards**

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International Standard IEC 61189-5-503 been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1433/FDIS	91/1443/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
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TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARD AND OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –

Part 5-503: General test method for materials and assemblies – Conductive anodic filaments (CAF) testing of circuit boards

1 Scope

This part of IEC 61189 specifies the conductive anodic filament (hereafter referred to as CAF) and specifies not only the steady-state temperature and humidity test, but also a temperature-humidity cyclic test and an unsaturated pressurized vapour test (HAST).

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60068-1:2013, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-30, *Environmental testing – Part 2-30: Tests – Test Db: Damp heat, cyclic (12 h + 12 h cycle)*

IEC 60068-2-38, *Environmental testing – Part 2-38: Tests – Test Z/AD: Composite temperature/humidity cyclic test*

IEC 60068-2-66, *Environmental testing – Part 2: Test methods – Test Cx: Damp heat, steady state (unsaturated pressurized vapour)*

IEC 60068-2-67, *Environmental testing – Part 2: Tests – Test Cy: Damp heat, steady state, accelerated test primarily intended for components*

IEC 60068-2-78, *Environmental testing – Part 2-78: Tests – Test Cab: Damp heat, steady state*

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IPC-TM-650 No.2.6.14.1, *Electrochemical Migration Resistance Test [viewed 2017-01-31]. Available at: https://www.ipc.org/TM/2-6_2-6-14-1.pdf*

IPC-TM-650 No.2.6.25, *Conductive Anodic Filament (CAF) Resistance Test: X-Y Axis [viewed 2017-01-31]. Available at: https://www.ipc.org/4.0_Knowledge/4.1_Standards/test/2-6-25.pdf*

3 Terms and definitions

For the purposes of this document, the terms and definitions given in IEC 60194 and IEC 60068-1 as well as the following apply.

ISO and IEC maintain terminological databases for use in standardization at the following addresses:

- IEC Electropedia: available at <http://www.electropedia.org/>
- ISO Online browsing platform: available at <http://www.iso.org/obp>

3.1

electrochemical migration

degradation of insulation characteristics between conductors due to electrochemical elution of ions in a humid environment when voltage is applied to conductors of a printed wiring board

Note 1 to entry: In addition, ionic impurities present in the insulations contribute to their degradation.

Note 2 to entry: Electrochemical migration may take the forms of dendrite (3.2) and CAF(3.3).

3.2

dendrite

metal migration

Note 1 to entry: Dendrite is visible in that it creates a branching and tree like structure on the surface, on the interface between layers, etc. of a printed wiring board.

3.3

CAF

conductive anodic filament

migration which occurs along the monofilament of reinforcing material such as glass cloth in an inner layer part of a printed wiring board

3.4

HAST

highly accelerated temperature and humidity stress test

stress test under unsaturated pressurized vapour test

Note 1 to entry: See IEC 60068-2-66.

3.5

automatic insulation resistance measurement

measurement to take continuous or predetermined periodic test data using an automatic measurement system without an operator

3.6

manual insulation resistance measurement

measurement to take predetermined periodic test data using measurement equipment by an operator

Note 1 to entry: Measurement can be done with or without taking out a specimen from the test chamber.

3.7

test voltage

voltage to apply on the specimen as a stress in the testing environment

3.8

measuring voltage

voltage to apply on the specimen in order to measure the insulation resistance

4 Testing condition

4.1 Standard condition

Measurement is performed under the standard atmospheric condition which is specified in Clause 4 of IEC 60068-1:2013.

It depends on a reference condition stated in 4.2 when an ambiguity is found for the judgment in the standard atmospheric condition or when it is required in particular.

It may be performed under other conditions than the standard atmospheric condition, when no doubt about the judgment subsists and when measuring in standard condition proves difficult, or when specified in particular specifications.

4.2 Judgment state

Reference condition is the standard atmospheric condition for measurement as stated in 4.2 of IEC 60068-1:2013.

5 Specimen

5.1 Outline of CAF test vehicle design

5.1.1 Evaluation design for the glass cloth direction

The in-line test combs are comprised of a series of alternate rows of via holes with a voltage applied across the comb. They represent the most common failure sites where CAF can occur: between via hole walls. The via holes are in line with one another and in alignment with the woven glass fibre reinforcement. The closest point between each via pair is the most likely point for CAF growth (example highlighted in Figure 1). The black spots represent the drilled hole, and the copper pads associated with the via holes are in orange.

The construction of staggered combs is similar to that of the in-line combs, however, the via pairs are arranged at 45°. This means that the most likely route for potential CAF growth is longer since the orientation of the glass fibres may only permit growth in the horizontal and vertical directions (as represented by the white ellipses in Figure 2).

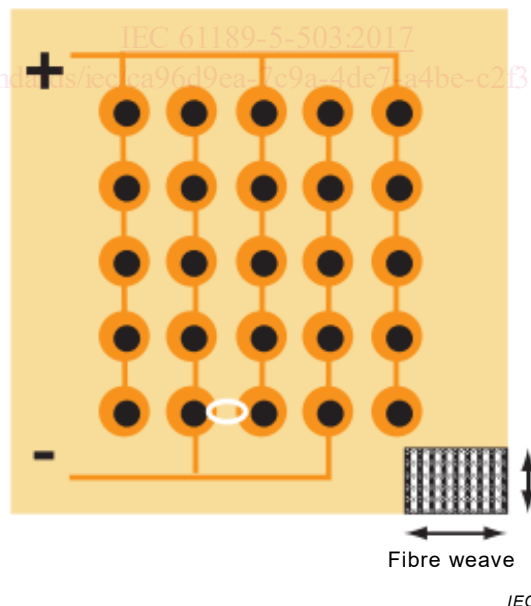


Figure 1 – Schematic of in-line test comb, with possible failure site